MICROWAVE POWER GaAs FET

Features

- · Low intermodulation distortion
 - IM₃ = -45 dBc at Po = 34.5 dBm, Single Carrier Level
- · High power
- P_{1dB} = 45 dBm at 6.4 GHz to 7.2 GHz
 High efficiency
- η_{add} = 36% at 6.4 GHz to 7.2 GHz
- High gain
 - G_{1dB} = 7.0 dB at 6.4 GHz to 7.2 GHz
- · Broadband internally matched
- · Hermetically sealed package

RF Performance Specifications (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Output Power at 1dB Compression Point	P _{1dB}	V _{DS} = 10V f = 6.4 ~ 7.2 GHz	dBm	44.0	45.0	-
Power Gain at 1dB Compression Point	G _{1dB}		dB	6.0	7.0	-
Drain Current	I_{DS}		Α	-	7.0	8.0
Power Added Efficiency	η_{add}		%	-	36	-
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-42	-45	-
Channel-Temperature Rise	ΔT_{ch}	V _{DS} x I _{DS} x R _{th (c-c)}	°C	-	_	100

Note 1: 2-tone Test Pout, Po = 34.5 dBm Single Carrier Level.

Electrical Characteristics (T_a = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max.
Transconductance	gm	V _{DS} = 3V I _{DS} = 10A	mS	_	6500	-
Pinch-off Voltage	V _{GSoff}	V _{DS} = 3V I _{DS} = 100 mA	V	-1.0	-2.5	-4.0
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	Α	_	18	22
Gate-Source Breakdown Voltage	V_{GSO}	I _{GS} = -350 μA	V	-5	-	-
Thermal Resistance	R _{th (c-c)}	Channel to Case	°C/W	-	1.0	1.3

The information contained here is subject to change without notice.

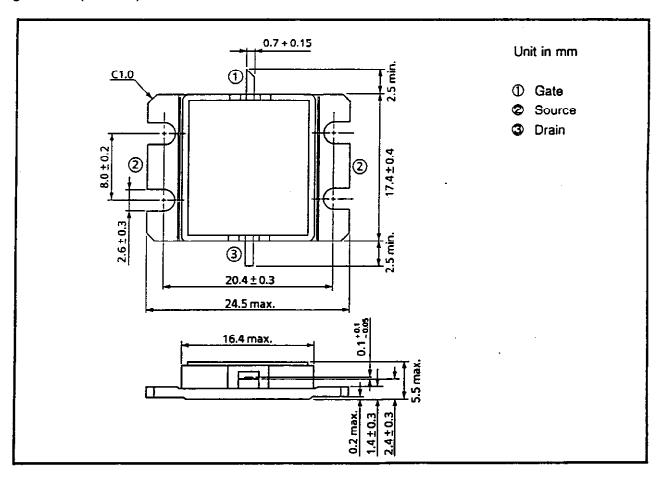
The information contained herein is presented only as guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA of TOSHIBA products are intended for usage in general electronic equipment, communication equipment, measuring equipment, domestic electrification, etc.) Please make sure that you consult with us before you use these TOSHIBA products in equipments which require high quality and/or reliability, and in equipments which could have major impact to the welfare of human life (atomic energy control, spaceship, traffic signal, combustion control, all types of safety devices, etc.). TOSHIBA cannot accept liability to any damage which may occur in case these TOSHIBA products were used in the mentioned equipments without prior consultation with TOSHIBA.

TOSHIBA CORPORATION MW50960196 1/4

Absolute Maximum Ratings ($T_a = 25^{\circ}C$)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V_{DS}	V	15
Gate-Source Voltage	V_{GS}	V	-5
Drain Current	I _{DS}	А	22
Total Power Dissipation (T _C = 25°C)	P _T	W	115
Channel Temperature	T _{ch}	.C	175
Storage Temperature	T _{stg}	.C	-65 ~ 175

Package Outline (2-16G1B)

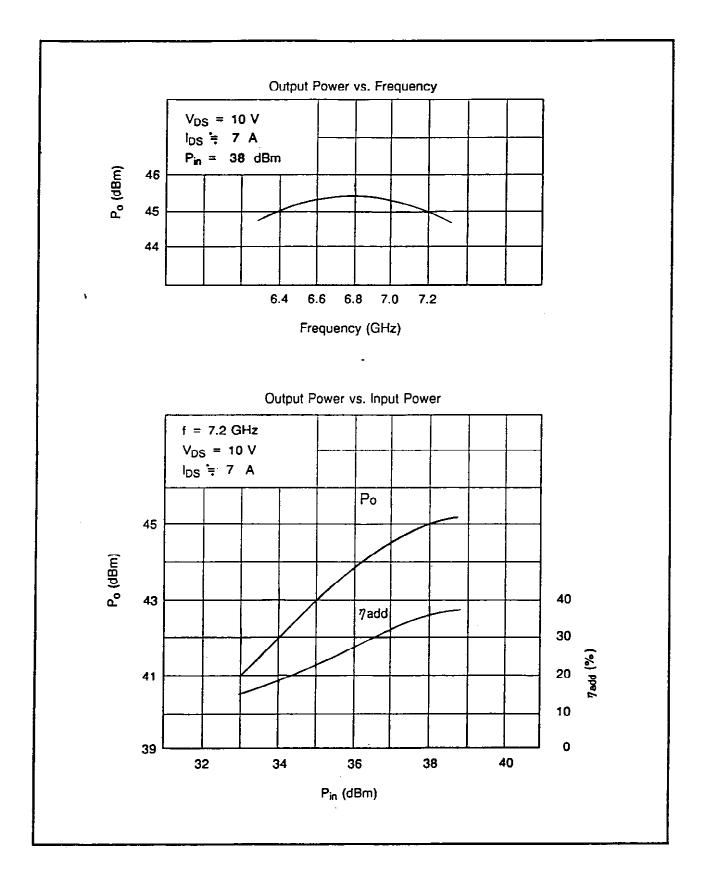


Handling Precautions for Packaged Type

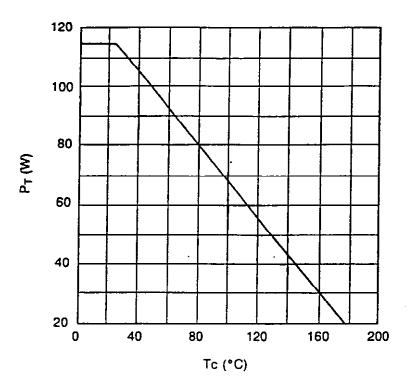
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

3/4

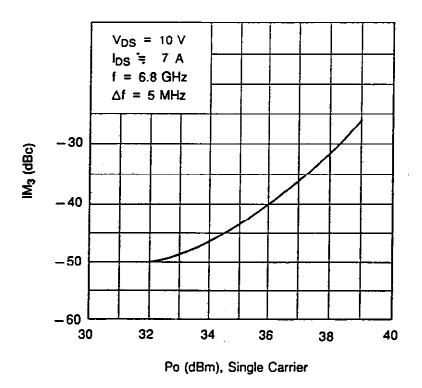
RF Performances



Power Dissipation vs. Case Temperature



IM₃ vs. Output Power Characteristics



4/4 MW50960196 TOSHIBA CORPORATION